

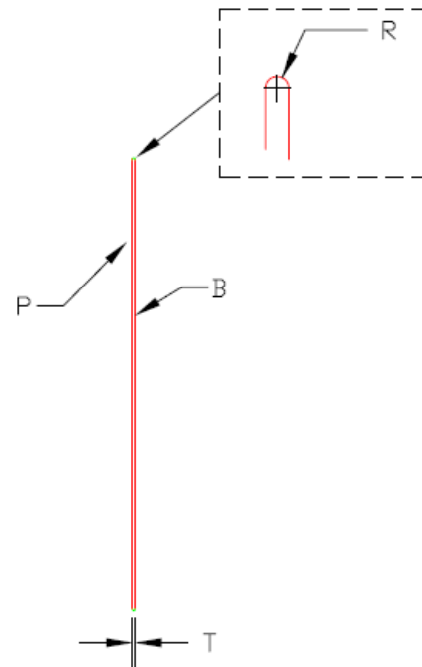
Quartz Wafer for SAW Application

Basic Specifications

Parameter	4" Wafer	Tolerance
Diameter (mm)	100	± 0.1 mm
Thickness (μm)	250, 350, 500	+10/-20 μm
Cut angle	Family of ST cuts (rotated Y-cut around the X axis about $25^\circ - 50^\circ$)	$\pm 5'$
X axis orientation	Parallel to the surface	$\pm 15'$
- Orientation	Perpendicular to the axis X	$\pm 15'$
Cut angle marking	With slots in the main flat, and/or on side of the wafer, by means of second flats, laser inscription below the primary flat	
Surface Quality - polished side - cut side	Polished SAW quality – RMS < 1 nm fine lapped (GC2000) - Ra = 0.12 - 0.20 μm	
Protective bevel - front side - back side	The edge of the wafer 0.2 mm 0.025 mm	+0.2 mm +0.175 mm
TTV [μm]	< 8	
MaxLTV [μm]	< 5 (an area of 13.6 x 13.6 mm)	
Bow [μm]	< 40	

* Above parameters can be consulted and customized according to the customer's requirements.

Drawing



CUSTOMER PRODUCT CODE		DESCRIPTION		REVISION	
MWF 0282				2008	
Designed by ADC	Checked by KS	Approved by - date 03/25/08		Date 03/25/08	
		DESCRIPTION			
		<div>ITEM NUMBER</div> <div>Sheet 1 OF 3</div>			